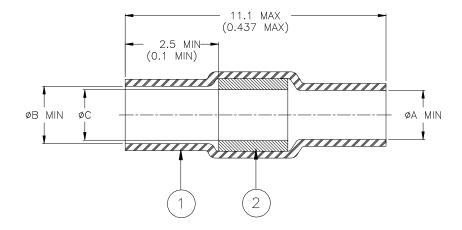
## **CUSTOMER DRAWING**



	Product Dimensions					
Product	øA¹	øB¹	$\phi$ C <sup>2</sup>			
Name	min	min				
D-110-6301	1.9	2.65	2.52±0.05			
	(0.075)	(0.105)	(0.010±0.002)			
D-110-6302	2.8	3.70	3.15±0.05			
	(0.110)	(0.145)	(0.124±0.002)			
D-110-6303	4.6	5.08	5.06±0.1			
	(0.180)	(0.200)	(0.200±0.004)			
D-110-6304	6.0	6.35	6.5±0.1			
	(0.235)	(0.250)	(0.255±0.004)			
D-110-6305	7.1	7.62	7.6±0.1			
	(0.280)	(0.300)	(0.300±0.004)			
D-110-6306	9.0	10.40	10.20±0.08			
	(0.355)	(0.410)	(0.402±0.003)			

- 1) As received minimum: Insulation diameter for wires entering this end must be less than this value.
- 2) Solder preform diameter: Combined conductor diameter must be less than this value.

## **MATERIALS**

- 1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked polyvinylidene fluoride.
- 2. SOLDER PREFORM WITH FLUX:

SOLDER: TYPE Sn63 per ANSI-J-STD-006. FLUX: TYPE ROL0 per ANSI-J-STD-004.

## APPLICATION

- 1. This part is designed for use in splicing wires rated for at least 125°C, having tin plated conductors.
- 2. When installed in accordance with TE Connectivity/Raychem Process Standard RCPS-100-70, parts will meet performance requirements of TE Connectivity/Raychem Specification RT-1404 for non-sealed splices.
- 3. Temperature rating:  $-55^{\circ}$ C to  $+150^{\circ}$ C.
- 4. Pre-tinning wires larger than 20AWG (use Sn63 solder) will decrease installation time and increase usable CMA

Raychem THERMOFIT DEVICES				SOLDERSLEEVE DEVICE*					
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]			D-110-630X						
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A		ES: N/A HNESS IN ON	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		REV:	2	DATE: 24-Jul-2020		
DRAWN BY: DATE: M. FORONDA 20-June-2		000	ECO: ECO-20-010292	SCALE:	NTS	SIZE: A	SHEET: 1 of 1		

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